

**TechConnect Ventures**

**Sprint Challenge Brief:**

**Additive manufacturing/3D printing of composite materials**

**BACKGROUND**

On behalf of multiple international corporations, TechConnect Ventures is seeking innovations and emerging technologies from around the world describing new materials and technologies for composite 3-D printing. Composite 3-D printed materials offer significant advantages over other materials due to enhanced mechanical properties such as strength, stiffness, toughness, wear resistance, and conductivity while preserving other 3-D printing advantages such as customization and low-cost. Traditional composite manufacturing requires significant skill, cost, and post-processing. Additive manufacturing systems that can handle composite materials have recently become of great interest for the wide variety of applications that composite materials serve including the automotive, aerospace, and biomedical industries.

**AREAS OF INTEREST**

Our clients are broadly interested in any technologies that improve the quality and manufacturability of 3-D printing of composite materials. Relevant areas of interest include, but are not limited to, materials and technologies for:

- Chopped fiber solutions
- Continuous fiber solutions
- Novel thermoset resins
- Manufactured composites with isotropic material properties
- Manufacturing approaches and hardware
- Optimization through software and design

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## BUSINESS OPPORTUNITY FOR SOLVERS

All complete and eligible Entries will be included in our exclusive Innovation Opportunity Report that will be presented to the innovation-seeking clients and partners. Solvers with well-matched capabilities may be contacted directly by consortium members to discuss potential partnership opportunities. Top-rated Entries may also be invited to register or participate in an upcoming TechConnect Ventures event or pitch program.

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## PARTICIPATION RULES & GUIDELINES

1. You must complete the provided Submission webform on the Sprint Submission page.
2. You are encouraged to submit a short presentation or pitch deck. A template is available on the Submission page.
3. **DO NOT INCLUDE ANY INFORMATION MARKED CONFIDENTIAL, PROPRIETARY, SENSITIVE OR CLASSIFIED. SUBMISSIONS MARKED AS SUCH WILL NOT BE SHARED WITH CLIENTS.**

Solvers should review the [Rules](#) and [Guidelines](#) provided on the Sprint page for details about participation, including submission criteria, eligibility information, and more.

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**QUESTIONS?** Contact Executive Director, Nick Kacsandi at [info@techconnectventures.com](mailto:info@techconnectventures.com)